

In the claims:

Please amend the claims 1 and 2 as follows:

1. An electronic circuit module comprising:  
at least one IC package unit, each unit having  
a carrier having first and second IC package mounting locations on opposed sides thereof, said first mounting location having a first mounting pad array, said second mounting location having a second mounting pad array, said first and second mounting pad arrays being coupled to a carrier interface; and  
a pair of IC packages, each package having a package body containing an integrated circuit chip and a plurality of connection elements coupled to said chip and extending at least to the surface of said body, the connection elements of said first package being conductively bonded to said first mounting pad array, the connection elements of said second package being conductively bonded to said second mounting pad array; and  
a printed circuit board having at least one interconnection pad array affixed thereto, each interconnection pad array coupled to circuitry on the printed circuit board and conductively bonded to the interface of a single IC package unit.
2. The electronic circuit module of claim 1, wherein individual mounting pads of said first mounting pad array are coupled to individual mounting pads of said second mounting pad array by means of conductive links within the carrier, and the connection elements of one of said IC packages are conductively bonded directly to said interconnection pad array.